



## Material Content Data Sheet



<b>Sales Product Name</b>		BSL307SP H6327		<b>Issued</b>		23. January 2018		
<b>MA#</b>		MA001136492						
<b>Package</b>		PG-TSOP6-6-6		<b>Weight*</b>		13.67 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	non noble metal	tin	7440-31-5	0.014	0.10		1000	
	noble metal	gold	7440-57-5	0.053	0.39		3877	
	inorganic material	silicon	7440-21-3	0.600	4.39	4.88	43936	48813
leadframe	inorganic material	silicon	7440-21-3	0.001	0.01		86	
	non noble metal	titanium	7440-32-6	0.006	0.04		432	
	non noble metal	chromium	7440-47-3	0.018	0.13		1297	
	non noble metal	copper	7440-50-8	5.882	43.04	43.22	430439	432254
wire	non noble metal	copper	7440-50-8	0.066	0.48	0.48	4821	4821
encapsulation	organic material	carbon black	1333-86-4	0.066	0.48		4793	
	plastics	epoxy resin	-	1.408	10.31		103058	
	inorganic material	silicondioxide	60676-86-0	5.077	37.15	47.94	371487	479338
leadfinish	non noble metal	tin	7440-31-5	0.299	2.19	2.19	21873	21873
plating	noble metal	silver	7440-22-4	0.176	1.29	1.29	12901	12901
*deviation	< 10%			Sum in total:		100.00		1000000

### Important Remarks:

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This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

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